Series HXP 200, SOT-227

200 W Power Resistor in the "ISOTOP" power device



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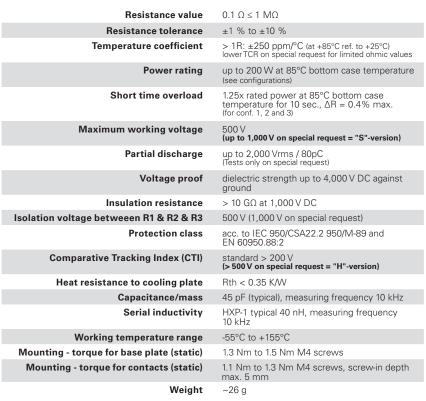
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Due to our Non-Inductive design, the HXP series is ideally suited for high-frequency and pulse-loading applications. Through direct mounting on a heat sink, significant cost advantage can be realized. Main applications are: variable speed drives, power supplies, control devices, telecommunications, robotics, motor controls and other switching devices.

Features

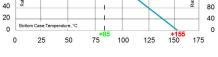
- multiple resistors in 1 package
- Non-Inductive design
- ROHS compliant
- Materials in accordance with UL 94 V-0
- AEC-Q200 compliant





100 80

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Derating (thermal resist.) HXP-200: 2.86 W/K (0.35 K/W) (for conf. 1, 2 and 3)

Best results can be reached by using a thermal transfer compound with a heat conductivity of at least 1 W/mK. The flatness of the cooling plate must be better than 0.05 mm overall. Surface roughness should not exceed 6.4 μ m.

How to make an order

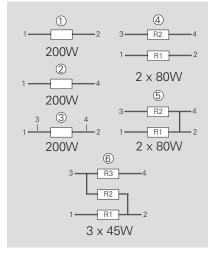
HXP-Configuration_Ohmic Value_Tolerance

For example:

HXP-1 1R 10% or HXP-4 2x50K 5%

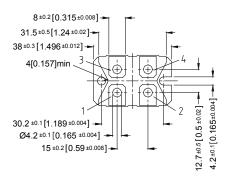
Example for higher working voltage or CTI HXP-4-S 2x40R 10% or HXPH-2 75K 5%

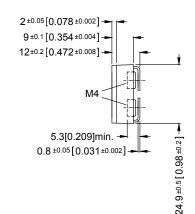
Configurations (P / package)



Version 5: ohmic value between contact 2 and 4 = $3m\Omega$

Dimensions in mm [inches]





The above spec, sheet features our standard products. For further options please contact our local EBG representative or contact us directly.

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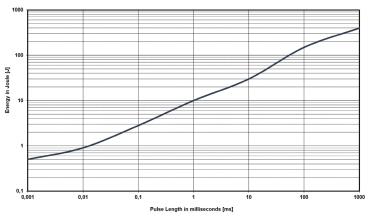
Pulse Energy Curve (typical rating for HXP 200)

Note: These energy values are reference values \rightarrow depending on ohmic value e.g. 1 Ω to 10 Ω and used resistive paste, a variation in max. energy load capability is possible

Test procedure

Every test resistor was mounted with thermal compound (0.9 W/mK) on a water cooled heatsink

- Constant inlet water temperature: +50°C
- The test time of each tested resistor: 10min.
- Break time between two pulses: 1sec.
- To determine good / defect parts the ohmic value was measured before and after tests: a change of tolerance of more than 0.1% means defect



Description of Pulse Energy Curve

- Shape of pulse = e-function
- Time between two pulses = 1 second
- Pulse length = time constant of 1 tau (1 means ... tau = 1ms)

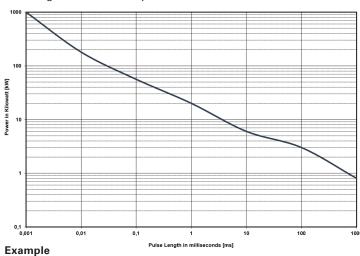
Example

At 1 ms tau the HXP 200 with e.g. 1 Ω to 10 Ω can withstand an energy level of about 10 J, when the pulse pause time is \geq 1s

At a symmetrical frequency > 1 kHz at pulse length ≥ 10 µsec. the maximum applied pulse energy for HXP 200 is a result out of the nominal power 200 W divided by the operating frequency (at 85°C bottom case) (E = 200 W / F)

Pulse Power Curve (typical rating for HXP 200)

The power curve shows the max. possible power which can be applied for a certain duration. Referring to the same test procedure as described above.



Description of Pulse Power Curve

- Shape of pulse = e-function
- Time between two pulses = 1 second
- Pulse length = time constant of 1 tau (1 means ... tau = 1ms)

For the time-constant of 1 ms you can apply about 20 kW max. (Pp = 2*E/T) \rightarrow , if the time between two such peaks is ≥ 1 s

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